exchange between: the medium; and the plate unit 10 and workpiece.

[0019] The heat insulation groove 16 is formed by communication of: grooves formed in the first disk member 11 and third disk member 13, the grooves each having a bottom; and a through hole formed in the second disk member 12, with each other. The heat insulation groove 16 is formed to surround the flow channel 15. An example in which the heat insulation groove 16 forms a closed space and the heat insulation groove 16 is vacuum inside will be described with respect to this embodiment, but the heat insulation groove 16 may be not vacuum, part of the heat insulation groove 16 may communicate with the outside and air may circulate through the heat insulation groove 16, or the inside of the heat insulation groove 16 may be filled with, for example, a solvent or resin high in thermostability.

[0020] Furthermore, the plate unit 10 includes a heater 18 provided more radially outward (outside) than the heat insulation groove 16. The heater 18 is driven under control by a control device not illustrated in the drawings. The heater 18 is configured by use of, for example, a heating wire, and is provided along the periphery of the first disk member 11. Upon installation of the placement board 1 in, for example, a semiconductor manufacturing apparatus, the heater 18 is electrically connected to a control device included in that semiconductor manufacturing apparatus. For example, the heater 18 is installed in the first disk member 11 by being covered with a sprayed film after being buried in a groove in the first disk member 11.

[0021] The connection unit 20 has, formed therein, a flow channel (not illustrated in the drawings) in which the